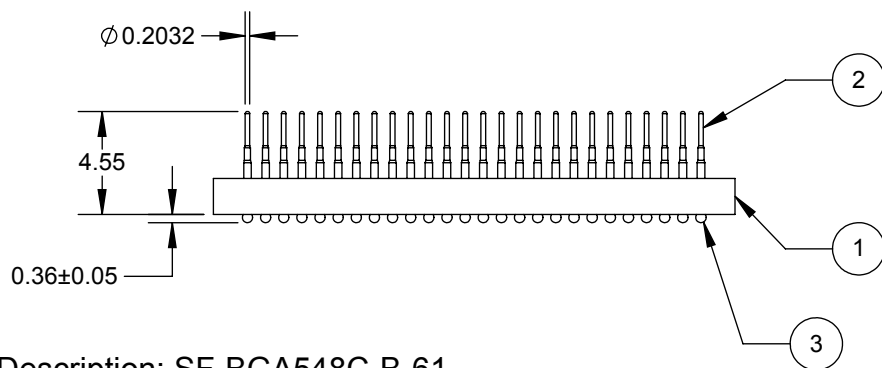


PART NO	DESCRIPTION
1	Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material; Non-clad
2	Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
3	Solder Balls: Sn96.5Ag3.0Cu0.5



Description: SF-BGA548C-B-61

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0254mm [±0.001"],
substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"]
unless stated otherwise. Materials and specifications are subject to change without notice.

PART NO. SUFFIX	SOLDER BALL ALLOY
-61	Sn63Pb37
-61F*	Sn96.5Ag3.0Cu0.5
*RoHS Compliant	

Rev	Date	Initials	Description
B	07/02/14	MR	P-T144A was P-T123A
C	1/9/15	MT	Converted to SW. Combined -61 and -61F parts.

SF-BGA548C-B-61 Specification
SF-BGA548C-B-61F Specification  Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com

Material: N/A
Finish: N/A
Weight: 2.80

STATUS: Released

ENG: M. Tully

FILE: SF-BGA548C-B-61 Dwg

SHEET: 1 OF 1

DRAWN BY: M. Raske

DATE: 09/03/2014

REV. C

SCALE: 3:1